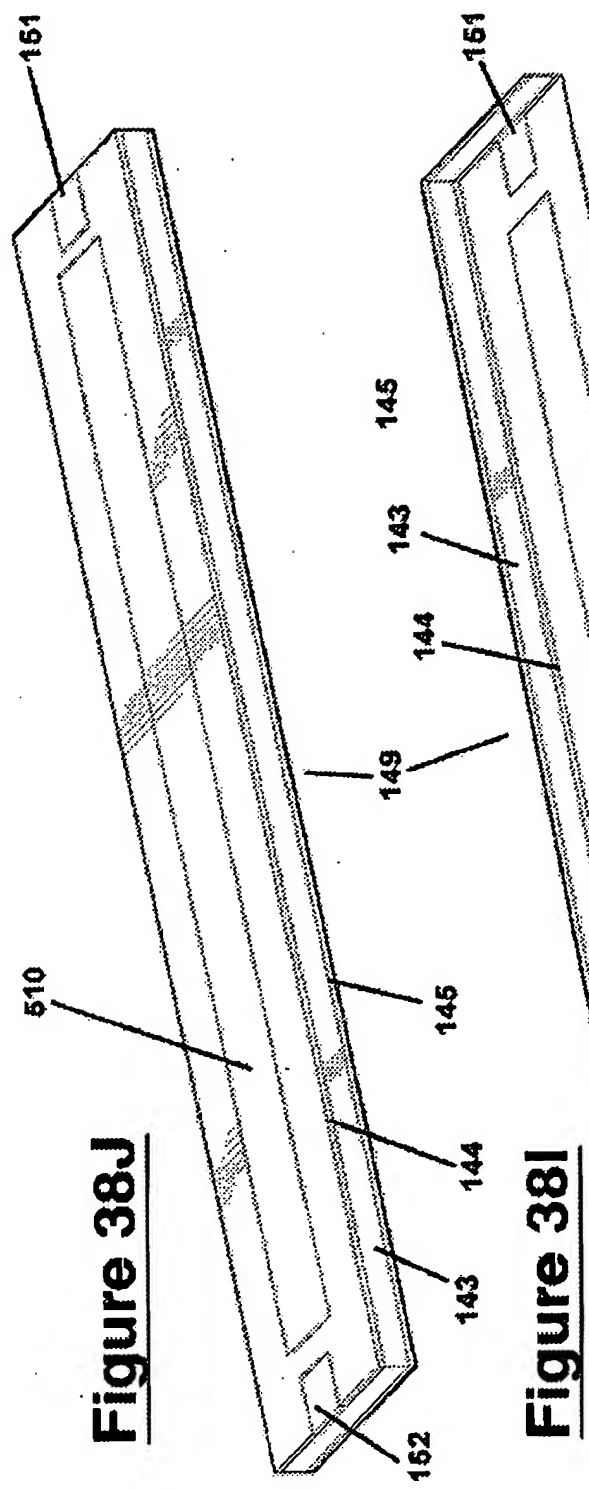
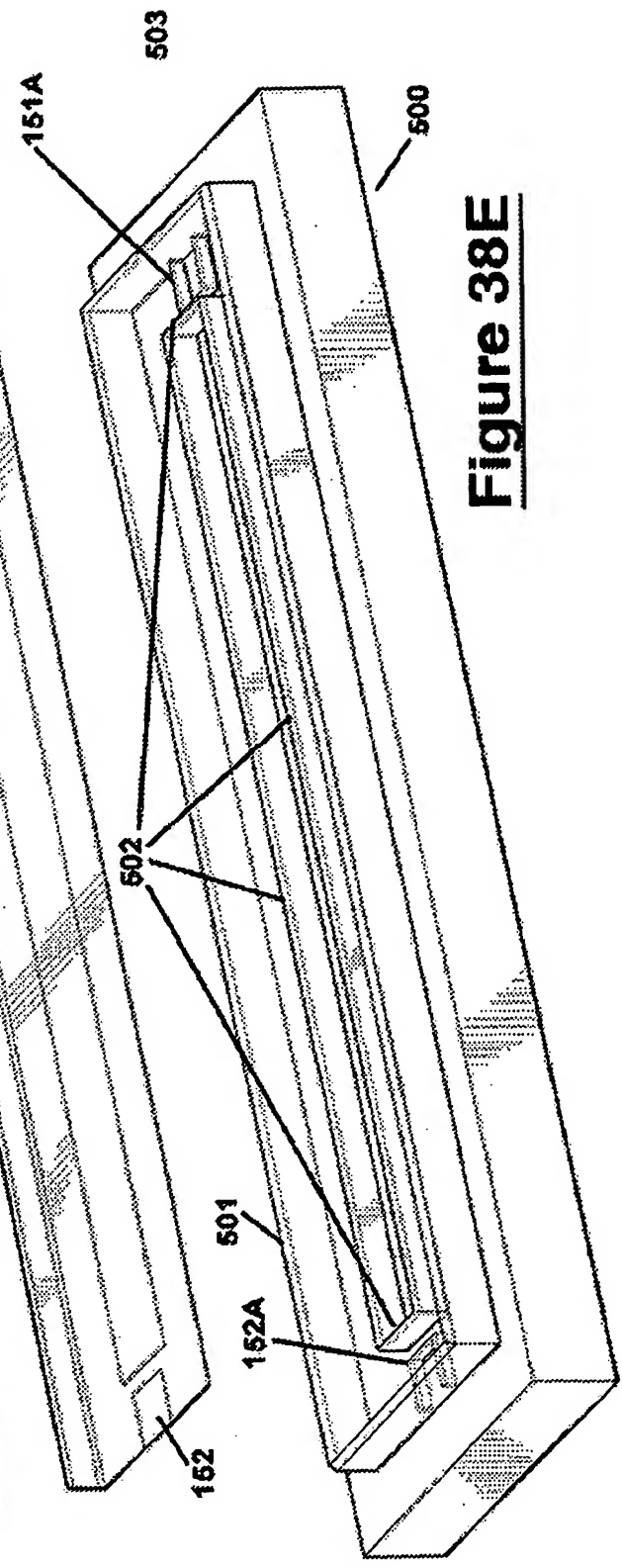


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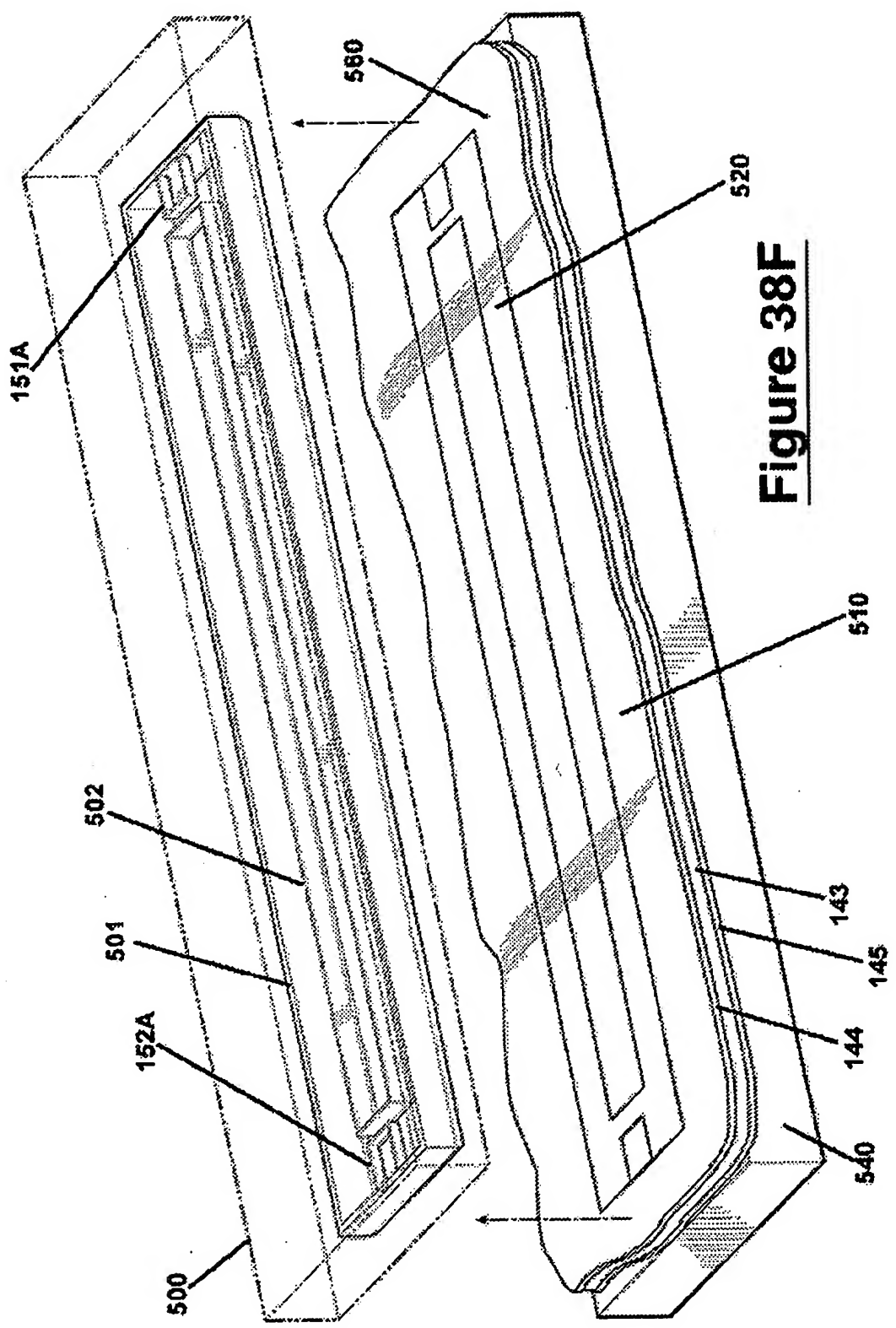


**Figure 38J**



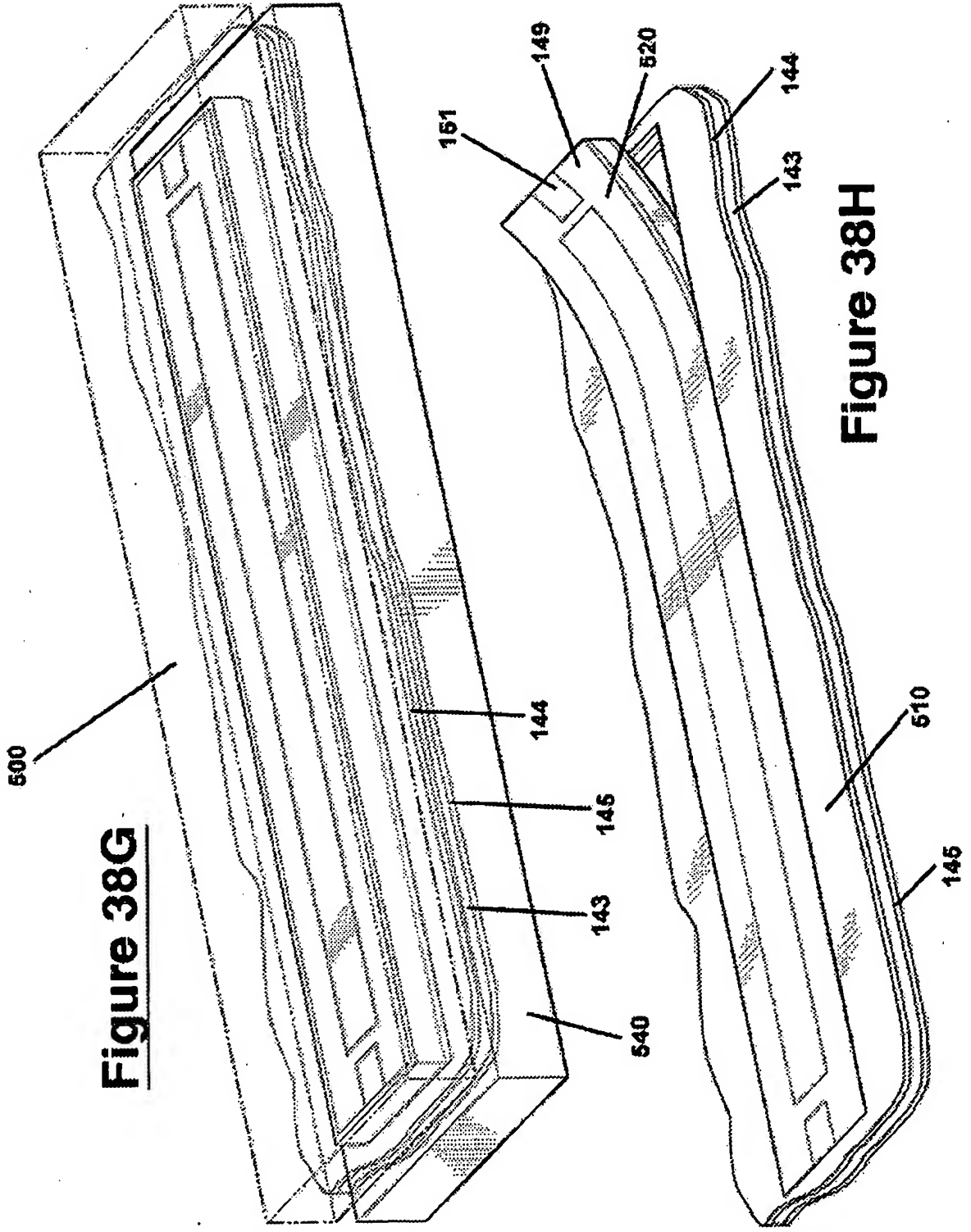
**Figure 38E**

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**Figure 38F**

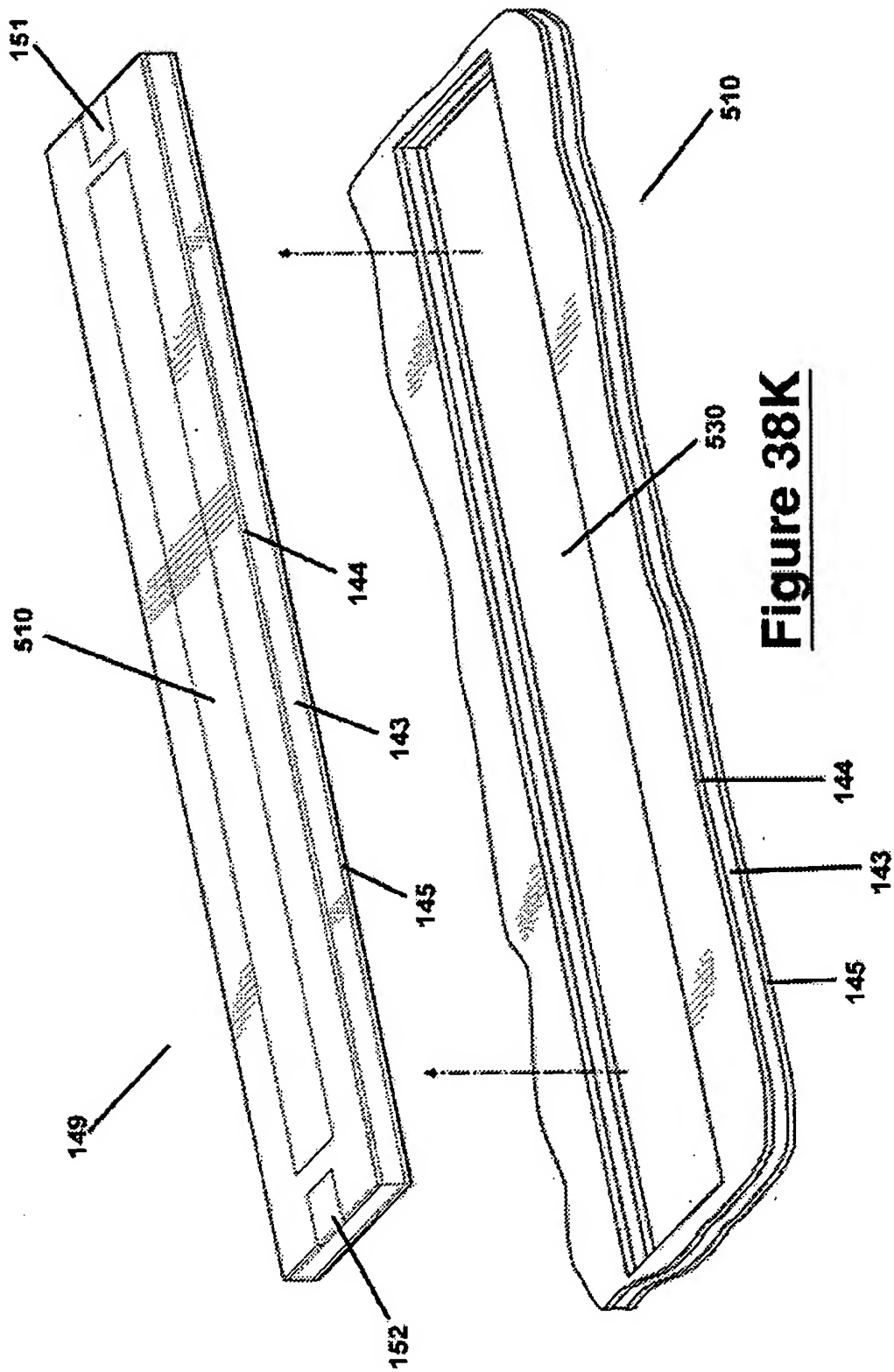
Do not enter. SK  
3/31/05



**Figure 38G**

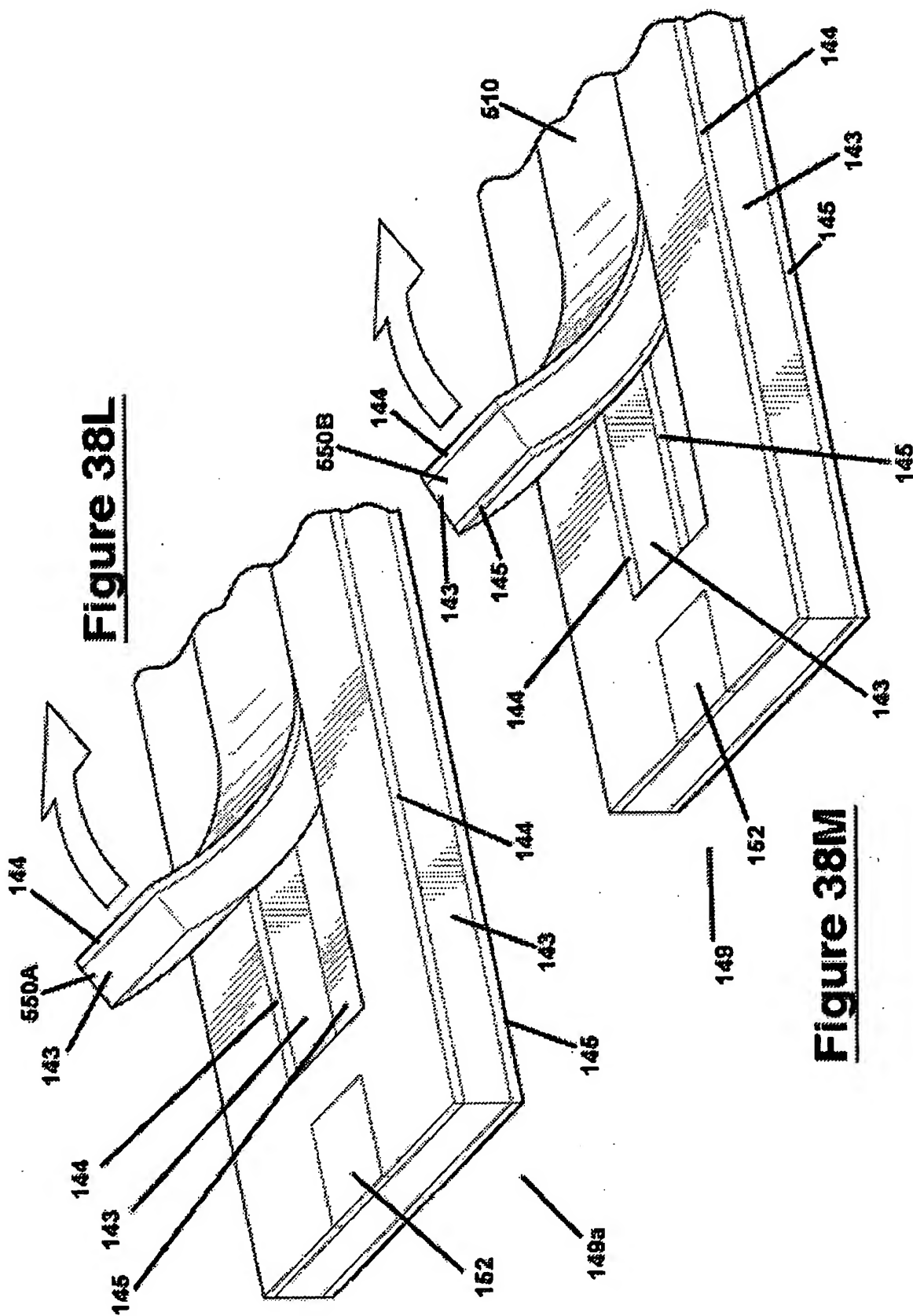
**Figure 38H**

Do not enter. SL  
3/31/05



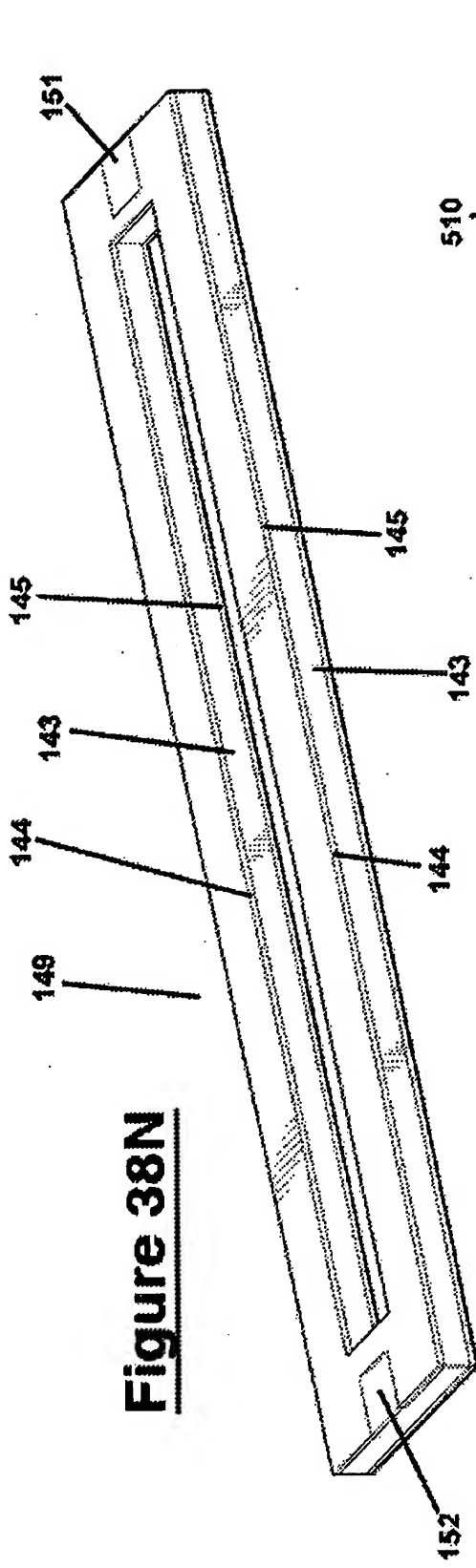
~~Do Not~~ Do Not Enter. *sf*  
3/31/05

**Figure 38L**

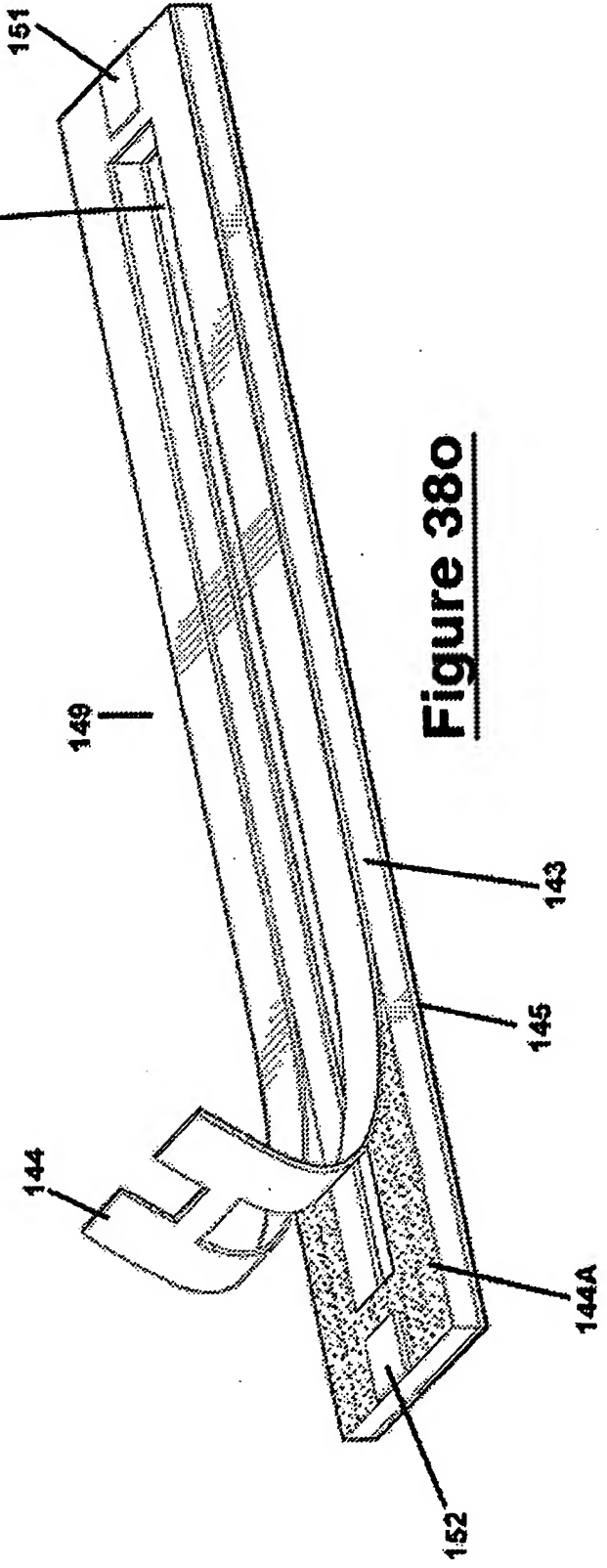


**Figure 38M**

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3/31/05

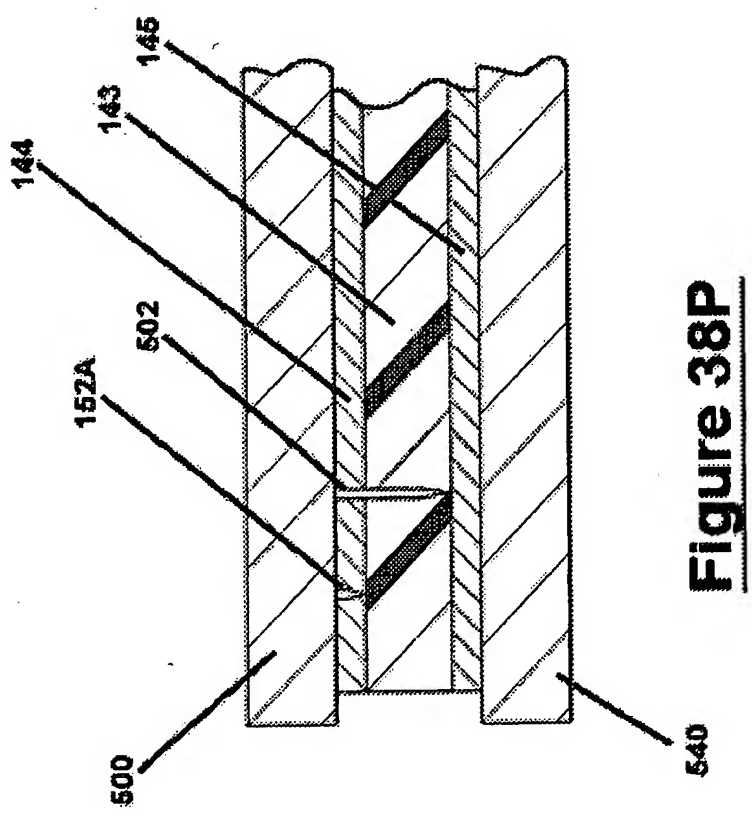


**Figure 38N**

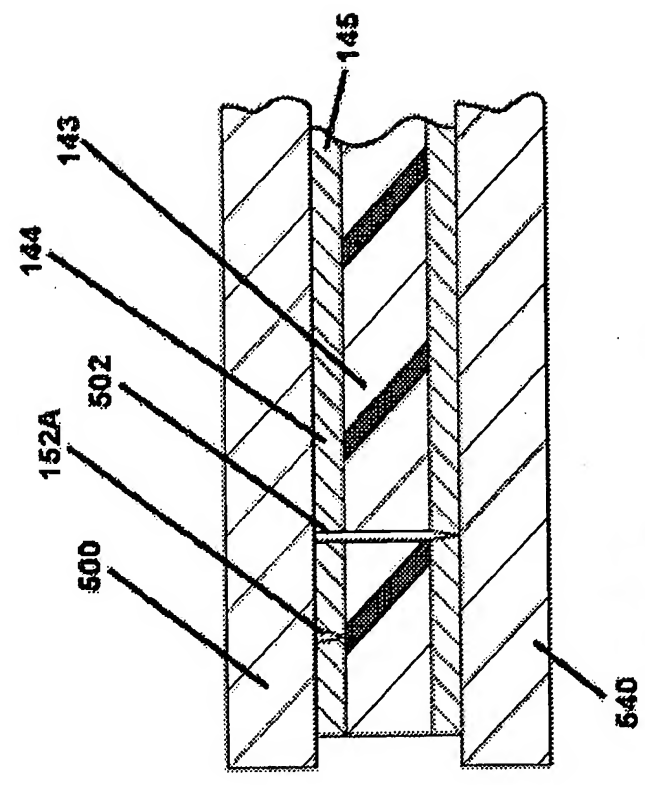


**Figure 38O**

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**Figure 38P**



**Figure 38Q**

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3/31/05

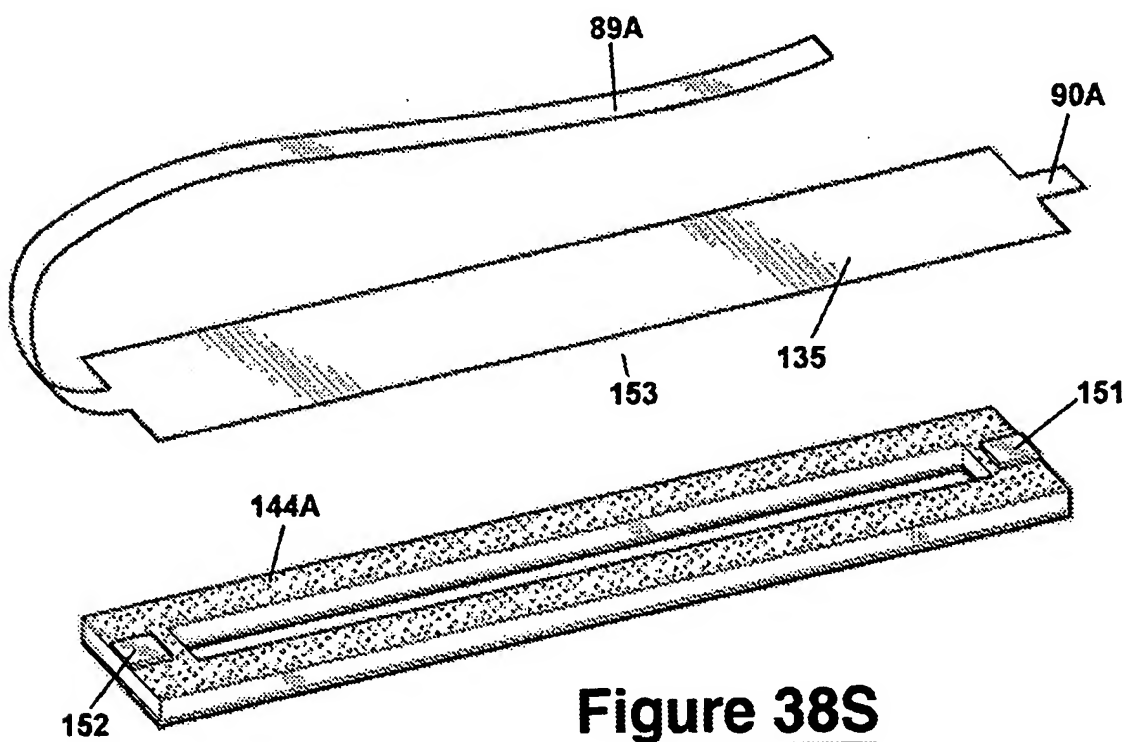
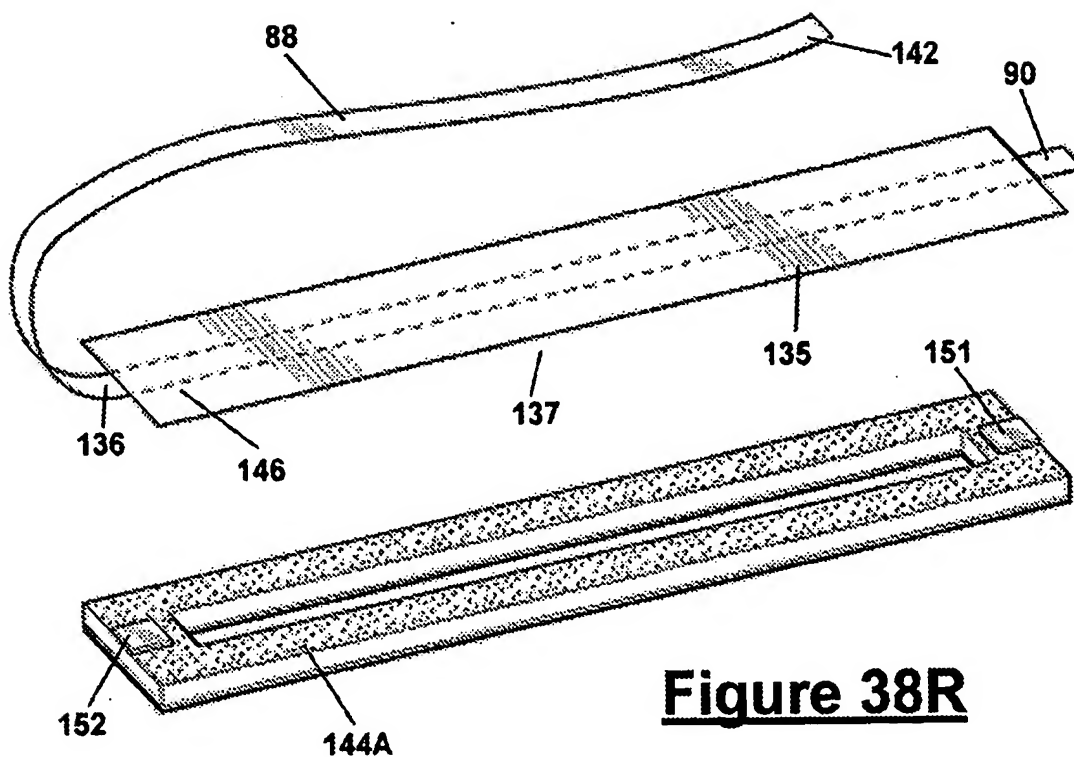
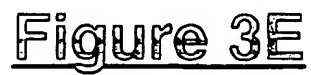




Figure 3C

Figure 3C is a perspective view of the device 109. The device 109 is a rectangular substrate with a dashed rectangular area representing the second electrode 93. A thin layer, labeled 92, is positioned on top of the device 109. This layer 92 has a portion 92A at one end and a portion 92B at the other end. A lead 89 is connected to the device 109. A contact pad 90 is also visible on the device 109.



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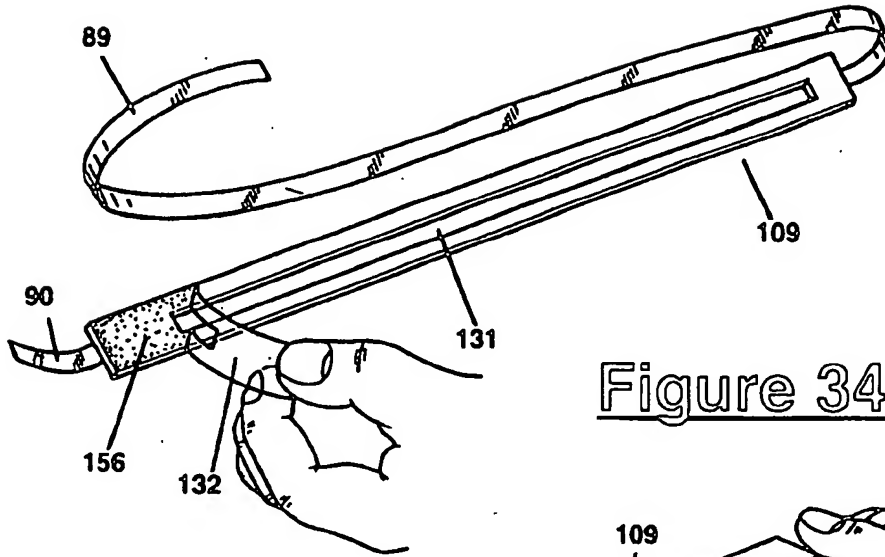


Figure 34

Figure 35

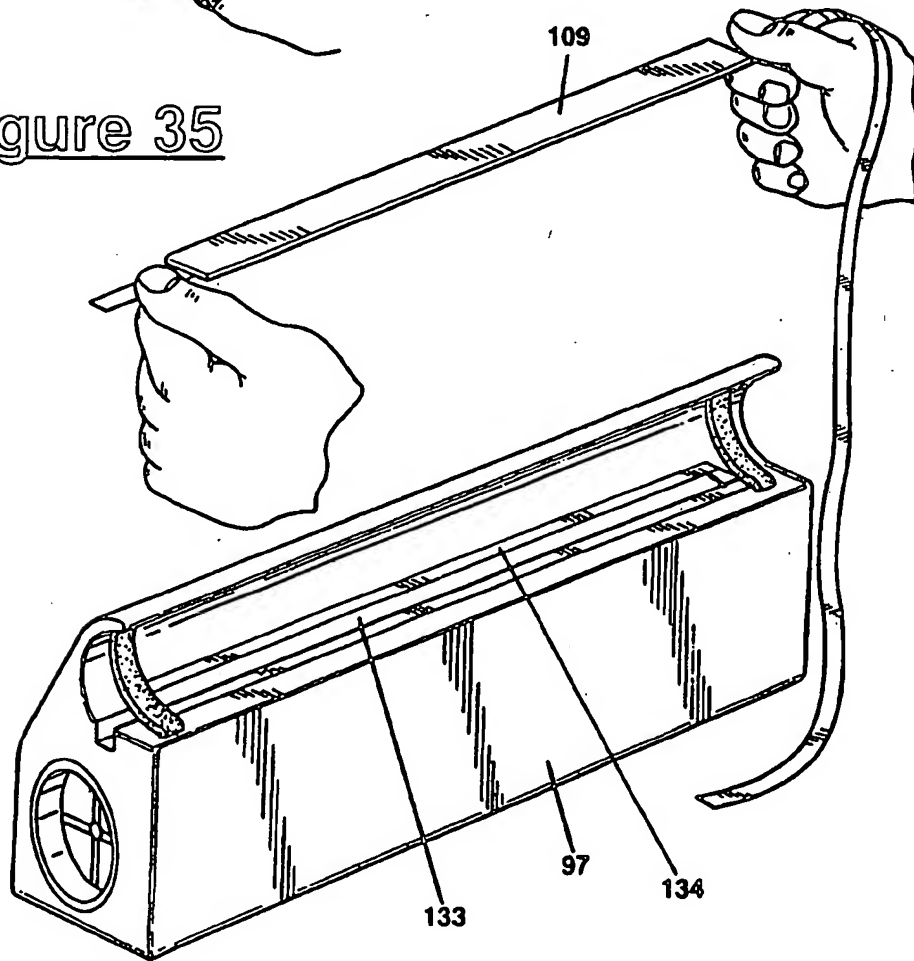


Figure 36

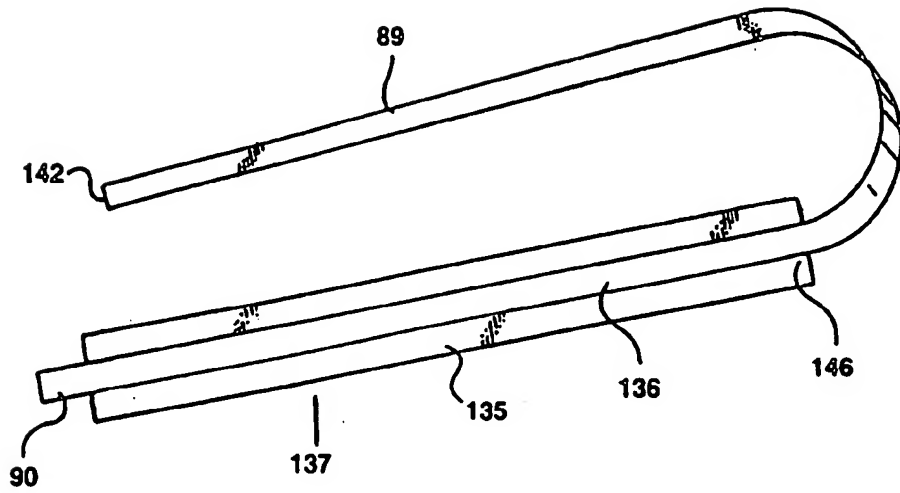
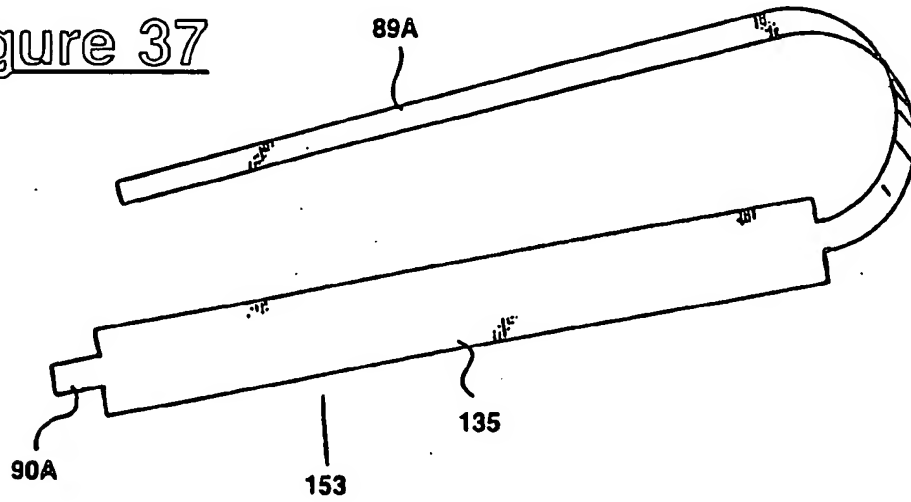


Figure 37



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